

Seeking technology and experts in epoxy solder paste development

- **SCHEDA**
- **APPROFONDIMENTI**

Identificativo proposta: TRSG20200814001

RICHIEDI MAGGIORI INFORMAZIONI

A Singapore SME is seeking technology partners with the relevant technology and expertise to co-develop epoxy solder paste formulations as an alternative bonding material. The new bonding material can be applied to soldering components such as flexible circuits, display panels and in other electronics component manufacturing. The SME is keen to seek partnerships in licensing, research or commercial agreements with technical assistance with startups and SMEs of all sizes.

With the growing demand for flexible printed circuits and rigid-flex circuits, the electronic components market is seeing new generations of materials being used for soldering and bonding. New product requirements also require a shift in how soldering and bonding will be done. Novel epoxy solder paste formulations present an alternative bonding solution that can be applied to soldering components such as flexible circuits and display panels. The Singapore SME, a soldering manufacturer is keen to explore the following partnerships with startups and SMEs of all sizes: i) Licensing agreements The Singapore SME will license the partner's technology to develop and commercialise it. ii) Research cooperation Both companies will jointly undertake research and further develop the technology. ii) Commercial agreements with technical assistance The partner will provide technical support to the Singapore company with the establishment of a commercial agreement.

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Tipo: Technology Request

Paese: Singapore

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